EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3883	(interpos$4 capos$4) with (substrate carrier board pcb) with (ball bga bump pin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 11:38
L2	1994	(flipchip (flip adj chip) semiconductor ic (integrated adj circuit) chip die dice electronic element) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 11:39
L3	1094	(pad land contact electrode terminal) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 12:41
L4	1094	(pad land contact electrode terminal) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 12:43
L5	31552	(bypass decoupling) with capacit$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 12:48
L6	34616	(bypass decoupl$4) with capacit$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 12:48
L7	55	6 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/24 12:49